# Low-Voltage CMOS Dual D-Type Flip-Flop

# With 5 V-Tolerant Inputs

The MC74LCX74 is a high performance, dual D-type flip-flop with asynchronous clear and set inputs and complementary  $(O, \overline{O})$  outputs. It operates from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A  $V_I$  specification of 5.5 V allows MC74LCX74 inputs to be safely driven from 5.0 V devices.

The MC74LCX74 consists of 2 edge-triggered flip-flops with individual D-type inputs. The flip-flop will store the state of individual D inputs, that meet the setup and hold time requirements, on the LOW-to-HIGH Clock (CP) transition.

#### **Features**

- Designed for 2.3 V to 3.6 V V<sub>CC</sub> Operation
- 5.0 V Tolerant Inputs Interface Capability With 5.0 V TTL Logic
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (10 μA)
   Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V

Machine Model >200 V

• These Devices are Pb-Free and are RoHS Compliant



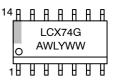
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http://onsemi.com

#### MARKING DIAGRAMS



SOIC-14 D SUFFIX CASE 751A

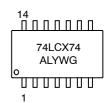




TSSOP-14 DT SUFFIX CASE 948G







A = Assembly Location

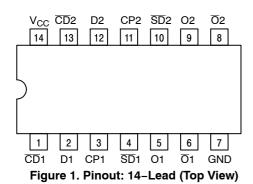
L, WL = Wafer Lot Y, YY = Year

W, WW = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.



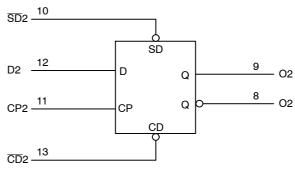


Figure 2. Logic Diagram

## **PIN NAMES**

Pins	Function
CP1, CP2	Clock Pulse Inputs
D1-D2	Data Inputs
CD1, CD2	Direct Clear Inputs
SD1, SD2	Direct Set Inputs
On- <del>O</del> n	Outputs

#### **TRUTH TABLE**

	Inputs			Outputs		
SDn	CDn	CPn	Dn	On	Ōn	Operating Mode
L	Н	Х	Х	Н	L	Asynchronous Set
Н	L	Х	Х	L	Н	Asynchronous Clear
L	L	Х	×	Н	Н	Undetermined
Н	Н	1	h	Н	L	
Н	Н	<b>↑</b>	I	L	Н	Load and Read Register
Н	Н	1	Х	NC	NC	Hold

H = High Voltage Level

h = High Voltage Level One Setup Time Prior to the Low-to-High Clock Transition

L = Low Voltage Level

= Low Voltage Level One Setup Time Prior to the Low-to-High Clock Transition

NC = No Change

X = High or Low Voltage Level and Transitions are Acceptable

= Low-to-High Transition

For  $I_{CC}$  reasons, DO NOT FLOAT Inputs

#### **MAXIMUM RATINGS**

Symbol	Parameter	Condition	Value	Units
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		$-0.5 \le V_1 \le +7.0$	V
Vo	DC Output Voltage	Output in HIGH or LOW State (Note 1)	$-0.5 \le V_O \le V_{CC} + 0.5$	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>I</sub> < GND	-50	mA
lok	DC Output Diode Current	V <sub>O</sub> < GND	-50	mA
		V <sub>O</sub> > V <sub>CC</sub>	+50	mA
Io	DC Output Source/Sink Current		±50	mA
I <sub>CC</sub>	DC Supply Current Per Supply Pin		±100	mA
I <sub>GND</sub>	DC Ground Current Per Ground Pin		±100	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Туре	Max	Units
V <sub>CC</sub>	Supply Voltage Operating Data Retention Only	2.0 1.5	2.5, 3.3 2.5, 3.3	3.6 3.6	V
VI	Input Voltage	0		5.5	V
Vo	Output Voltage (HIGH or LOW State) (3-State)	0		V <sub>CC</sub>	V
Гон	HIGH Level Output Current V <sub>CC</sub> = 3.0 V - 3.6 V V <sub>CC</sub> = 2.7 V - 3.0 V V <sub>CC</sub> = 2.3 V - 2.7 V			-24 -12 -8	mA
l <sub>OL</sub>	LOW Level Output Current $V_{CC} = 3.0 \text{ V} - 3.6 \text{ V}$ $V_{CC} = 2.7 \text{ V} - 3.0 \text{ V}$ $V_{CC} = 2.3 \text{ V} - 2.7 \text{ V}$			+24 +12 +8	mA
T <sub>A</sub>	Operating Free-Air Temperature	-40		+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V <sub>IN</sub> from 0.8 V to 2.0 V, V <sub>CC</sub> = 3.0 V	0		10	ns/V

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74LCX74DG	SOIC-14 (Pb-Free)	55 Units / Rail
MC74LCX74DR2G	SOIC-14 (Pb-Free)	2500 Tape & Reel
MC74LCX74DTG	TSSOP-14*	96 Units / Rail
MC74LCX74DTR2G	TSSOP-14*	2500 Tape & Reel
MC74LCX74MELG	SOEIAJ-14 (Pb-Free)	2000 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>1.</sup> I<sub>O</sub> absolute maximum rating must be observed.

<sup>\*</sup>This package is inherently Pb-Free.

#### DC ELECTRICAL CHARACTERISTICS

			T <sub>A</sub> = −40°C		
Symbol	Characteristic	Condition	Min	Max	Units
V <sub>IH</sub>	HIGH Level Input Voltage (Note 2)	2.3 V ≤ V <sub>CC</sub> ≤ 2.7 V	1.7		V
		2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V	2.0		
V <sub>IL</sub>	LOW Level Input Voltage (Note 2)	2.3 V ≤ V <sub>CC</sub> ≤ 2.7 V		0.7	V
		2.7 V ≤ V <sub>CC</sub> ≤ 3.6 V		0.8	
V <sub>OH</sub>	HIGH Level Output Voltage	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OH} = -100 \mu\text{A}$	V <sub>CC</sub> - 0.2		V
		V <sub>CC</sub> = 2.3 V; I <sub>OH</sub> = -8 mA	1.8		
		V <sub>CC</sub> = 2.7 V; I <sub>OH</sub> = -12 mA	2.2		1
		V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -18 mA	2.4		1
		V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -24 mA	2.2		
V <sub>OL</sub>	LOW Level Output Voltage	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OL} = 100 \mu\text{A}$		0.2	V
		V <sub>CC</sub> = 2.3 V; I <sub>OL</sub> = 8 mA		0.6	
		V <sub>CC</sub> = 2.7 V; I <sub>OL</sub> = 12 mA		0.4	1
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 16 mA		0.4	
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 24 mA		0.55	1
I <sub>I</sub>	Input Leakage Current	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; 0 \text{ V} \le \text{V}_{I} \le 5.5 \text{ V}$		±5	μΑ
I <sub>CC</sub>	Quiescent Supply Current	$2.3 \le V_{CC} \le 3.6 \text{ V}; V_I = \text{GND or } V_{CC}$		10	μΑ
		$2.3 \le V_{CC} \le 3.6 \text{ V}; 3.6 \le V_{I} \text{ or } V_{O} \le 5.5 \text{ V}$		±10	1
$\Delta I_{CC}$	Increase in I <sub>CC</sub> per Input	$2.3 \le V_{CC} \le 3.6 \text{ V}; V_{IH} = V_{CC} - 0.6 \text{ V}$		500	μΑ

<sup>2.</sup> These values of  $V_{\rm I}$  are used to test DC electrical characteristics only.

## AC CHARACTERISTICS $t_R$ = $t_F$ = 2.5 ns; $R_L$ = 500 $\Omega$

					Lin	nits			
					T <sub>A</sub> = -40°	C to +85°C	;		
			V <sub>CC</sub> = 3.3	3 V ± 0.3 V	V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = 2.5	5 V ± 0.2 V	
			C <sub>L</sub> =	50 pF	C <sub>L</sub> =	50 pF	C <sub>L</sub> =	30 pF	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Units
f <sub>max</sub>	Clock Pulse Frequency	1	150		150		150		MHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay CPn to On or On	1	1.5 1.5	7.0 7.0	1.5 1.5	8.0 8.0	1.5 1.5	8.4 8.4	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay SDn or CDn to On or On	2	1.5 1.5	7.0 7.0	1.5 1.5	8.0 8.0	1.5 1.5	8.4 8.4	ns
ts	Setup Time, HIGH or LOW Dn to CPn	1	2.5		2.5		4.0		ns
t <sub>h</sub>	Hold Time, HIGH or LOW Dn to CPn	1	1.5		1.5		2.0		ns
t <sub>w</sub>	CPn Pulse Width, HIGH or LOW SDn or CDn Pulse Width, LOW	4	3.3 3.3		3.3 3.6		4.0 4.0		ns
t <sub>rec</sub>	Recovery Time SDn or CDn to CPn	3	2.5		3.0		4.5		ns
t <sub>OSHL</sub> t <sub>OSLH</sub>	Output-to-Output Skew (Note 3)			1.0 1.0					ns

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

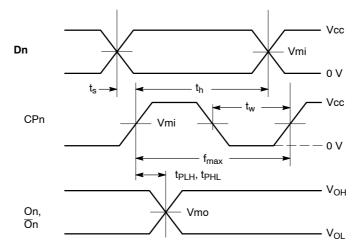
#### **DYNAMIC SWITCHING CHARACTERISTICS**

			T <sub>A</sub> = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Max	Units
V <sub>OLP</sub>	Dynamic LOW Peak Voltage (Note 4)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V} $ $V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$		0.8 0.6		V V
V <sub>OLV</sub>	Dynamic LOW Valley Voltage (Note 4)	$\begin{array}{c} V_{CC} = 3.3 \text{ V, } C_L = 50 \text{ pF, } V_{IH} = 3.3 \text{ V, } V_{IL} = 0 \text{ V} \\ V_{CC} = 2.5 \text{ V, } C_L = 30 \text{ pF, } V_{IH} = 2.5 \text{ V, } V_{IL} = 0 \text{ V} \end{array}$		-0.8 -0.6		V

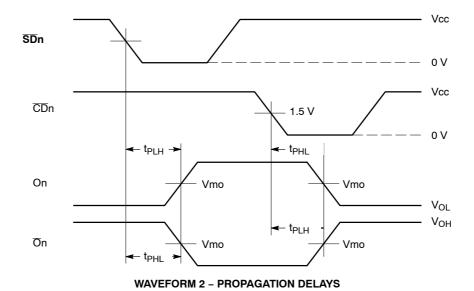
<sup>4.</sup> Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

## **CAPACITIVE CHARACTERISTICS**

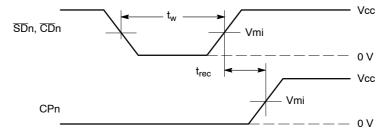
Symbol	Parameter	Condition	Typical	Units
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	7	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, $V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	25	pF



WAVEFORM 1 – PROPAGATION DELAYS, SETUP AND HOLD TIMES  $t_{R}=t_{F}=2.5~\text{ns},~10\%~\text{to}~90\%;~f=1~\text{MHz};~t_{W}=500~\text{ns}$ 

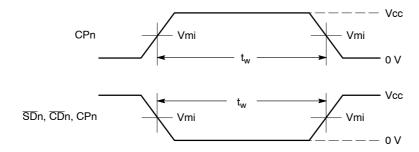


 $t_R$  =  $t_F$  = 2.5 ns, 10% to 90%; f = 1 MHz;  $t_W$  = 500 ns Figure 3. AC Waveforms



## **WAVEFORM 3 - RECOVERY TIME**

 $t_R$  =  $t_F$  = 2.5 ns from 10% to 90%; f = 1 MHz;  $t_w$  = 500 ns

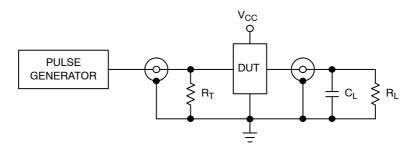


#### **WAVEFORM 4 - PULSE WIDTH**

 $t_R$  =  $t_F$  = 2.5 ns (or fast as required) from 10% to 90%; Output requirements:  $V_{OL} \le 0.8 \text{ V}, V_{OH} \ge 2.0 \text{ V}$ 

	Vcc					
Symbol	3.3 V <u>+</u> 0.3 V	2.7 V	2.5 V <u>+</u> 0.2 V			
Vmi	1.5 V	1.5 V	Vcc/2			
Vmo	1.5 V	1.5 V	Vcc/2			

Figure 3. AC Waveforms (Continued)



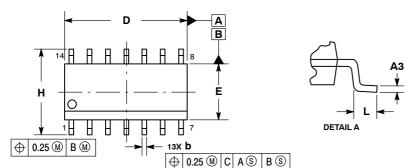
 $C_L=50$  pF at  $V_{CC}=3.3\pm0.3$  V or equivalent (includes jig and probe capacitance)  $C_L=30$  pF at  $V_{CC}=2.5\pm0.2$  V or equivalent (includes jig and probe capacitance)  $R_L=R_1=500~\Omega$  or equivalent

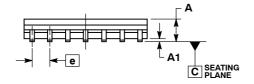
 $R_T = Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

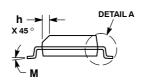
Figure 4. Test Circuit

## **PACKAGE DIMENSIONS**

#### SOIC-14 NB CASE 751A-03 ISSUE K







- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

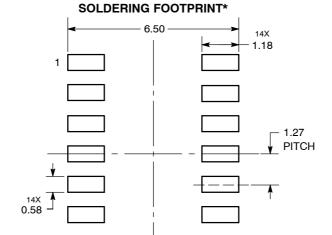
  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.

  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.

  5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
АЗ	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
Е	3.80	4.00	0.150	0.157
е	1.27	BSC	0.050	BSC
Н	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
М	0 °	7°	0 °	7 °

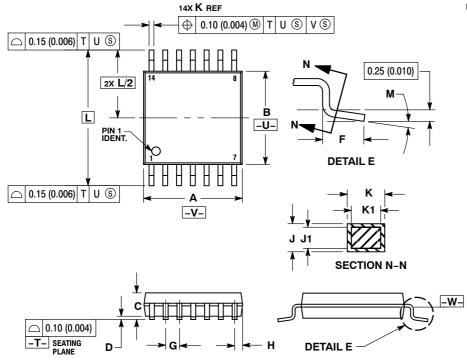


DIMENSIONS: MILLIMETERS

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

#### TSSOP-14 CASE 948G-01 **ISSUE B**



- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

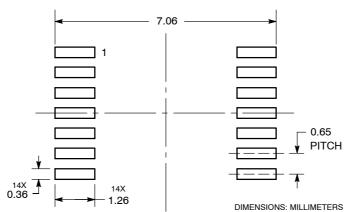
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  - CONDITION.
    6. TERMINAL NUMBERS ARE SHOWN FOR
  - REFERENCE ONLY.

    7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

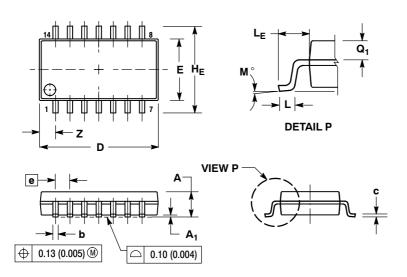
	MILLIN	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
Н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
Κ	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40	BSC	0.252 BSC	
M	0 °	8 °	0 °	8 °

#### **SOLDERING FOOTPRINT**



#### PACKAGE DIMENSIONS

SOEIAJ-14 CASE 965-01 **ISSUE B** 



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982
- Y 14.3M, 1962.

  CONTROLLING DIMENSION: MILLIMETER.

  DIMENSIONS D AND E DO NOT INCLUDE
  MOLD FLASH OR PROTRUSIONS AND ARE
  MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- I. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION, ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 ( 0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.10	0.20	0.004	0.008
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10°	0 °	10°
$Q_1$	0.70	0.90	0.028	0.035
Z		1.42		0.056

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